To the Honorable Commissioner for Patents and Trademarks: Please record the attached original documents or copy thereto:

1. Name of Conveying Party(ies):
   Yasutaka TOYODA, Akiyuki SUGIYAMA, Ryoichi MATSUOKA, Takumichi SUTANI, Hidemitsu NAYA

2. Name and address of receiving party(ies):
   Name: HITACHI HIGH-TECHNOLOGIES CORPORATION
   Address: 24-14, Nishishinbashı 1-chome, Minato-ku, Tokyo, JAPAN

3. Nature of Conveyance:
   □ Assignment
   □ Merger
   □ Security Agreement
   □ Change of Name
   □ Other

   Execution Date: August 9, 2006, August 10, 2006, August 9, 2006, August 10, 2006, August 21, 2006 (respectively)

   Additional name(s) & address(es) attached? □ Yes □ No

4. Application number(s) or patent number(s):
   If the document is being filed together with a new application, the execution date of the application is:
   A. Patent Application No(s).
      11/453,229 filed on June 15, 2006
   B. Patent No(s).

      Additional numbers attached? □ Yes □ No

5. Name and address of party to whom correspondence concerning document should be mailed:
   Name: MCDERMOTT WILL & EMERY LLP
   Internal Address:

   Street Address: 600 13th Street, N.W.

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41) $40.00
   □ Enclosed
   □ Authorized to be charged to deposit account

8. Deposit account number: 500417

   To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is true copy of the original document.

   Brian K. Seidleck Reg. No 54,321
   Keith E. George, Registration No. 34,111

   Name and Registration No. of Person Signing
   Signature
   DoE 9/23/2006
   September 13, 2006

   Total number of pages including cover sheet: 2
ASSIGNMENT
(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar ($1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi High-Technologies Corporation, a corporation organized under the laws of Japan, located at 24-14, Nishishinbashishi 1-chome, Minato-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi High-Technologies Corporation, its successors and assigns, all my right, title and interest, in and to

METHOD AND APPARATUS OF PATTERN INSPECTION AND SEMICONDUCTOR INSPECTION SYSTEM USING THE SAME

※ U.S. application number 11/453229 filed on June 15, 2006 invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi High-Technologies Corporation, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi High-Technologies Corporation.

Signed on the date(s) indicated aside signatures:

1) Yasutaka TOYODA
   Date Signed 8/9/06
2) Akiyuki SUGIYAMA
   Date Signed 8/10/06
3) Ryoichi MATSUOKA
   Date Signed 8/9/06
4) Takumichi SUTANI
   Date Signed 8/10/06
5) Hidemitsu NAYA
   Date Signed 8/21/06

RECORDED: 09/13/2006